**Design & Dimensioned in Millimeters/Inches**

_SMA-J-P-X-ST-EM1_
- **Gender:** J: Jack
- **Type:** P: PCB
- **Termination:** EM1: Edge Mount
- **Orientation:** ST: Straight

**Plating Specification**
- "H: 30µ" Gold Center Contact, 3µ" Gold Outer Contact

(See Table 1)

**Recommended PCB Layout**
- _Board Thickness: 1.57 mm_

**Table 1**

<table>
<thead>
<tr>
<th>Item</th>
<th>Component</th>
<th>- H</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Shell</td>
<td>SMA-J-P-F-ST-EM1-SHL</td>
</tr>
<tr>
<td>2</td>
<td>Insulator</td>
<td>SMA-INS-006</td>
</tr>
<tr>
<td>3</td>
<td>Socket</td>
<td>SMA-SKT-005-H</td>
</tr>
</tbody>
</table>

**Material:**
- Shell: Brass
- Socket: Copper Alloy
- Dielectric: PTFE

**Proprietary Note:**
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**Notes:**
1. Represents a critical dimension.
2. Stake around circumference 4 indents equally spaced.
4. Center contact pushout force: 0.05±.05 [.002±.002] to insulator
5. Parts to be packaged in trays; if quantity is less than half tray, parts to be packaged in cohesive foam.
6. Notes deleted.
7. Note deleted.
8. Note deleted.

**Revision:**
- **G**

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**Sheet Scale:** 4:1

**F:DWG\MISC\MARKET\SMA-J-P-X-ST-EM1-MKT.SLDDRW**